

STZ150NF55T

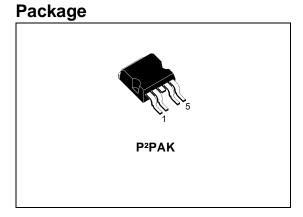
N-CHANNEL TEMPERATURE SENSING 55V - P²PAK SAFeFET™ MOSFET

DATA BRIEF

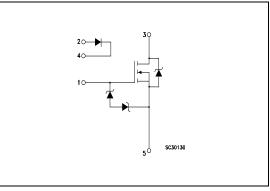
General features

Туре	V _{DSSS}	R _{DS(on)}	Ι _D
STZ150NF55T	55 V	<9 mΩ	40 A(1)

- INTEGRATED ESD PROTECTION
- INTEGRATED TEMPERATURE SENSING
- STANDARD VGS(th) LEVEL
- 175°C JUNCTION TEMPERATURE



Internal schematic diagram



Applications

■ HIGH CURRENT SWITCHING

Order codes

Sales Type	Marking	Package	Packaging
STZ150NF55T	STZ150NF55T Z150NF55T		TAPE & REEL

1 Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V _{DS}	Drain-Source Voltage (V _{GS} = 0)	55	V	
V _{GS}	Gate-Source Voltage	± 18	V	
I _D Note 1	Drain Current (continuous) at T _C = 25°C	40	А	
I _D Note 1	Drain Current (continuous) at T _C = 100°C	40	Α	
I _{DM}	Drain Current (pulsed)	160	Α	
P _{TOT}	Total Dissipation at T _C = 25°C	250	W	
	Derating Factor	1.67	W/°C	
Vesd(G-S)	G-S ESD (HBM C=100pF, R=1.5kΩ)	>4	kV	
E _{AS}	Single Pulse Avalanche Energy	TBD	mJ	
T _j T _{stg}	Operating Junction Temperature -55 to 175 Storage Temperature -55 to 175		°C	

 Table 1.
 Absolute maximum ratings



2 Electrical characteristics

 $(T_{CASE} = 25 \text{ °C unless otherwise specified})$

Table 2.	On/Off
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Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μΑ, V _{GS} = 0	55			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating,			10	μA
I _{GSS}	Gate Body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 15V, V_{DS} = 0$			10	μA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V
R _{DS(on)}	Static Drain-Source On Resistance	V _{GS} = 10 V, I _D = 20 A			9	mΩ
V _F	Temperature Sense diode forward voltage	Ι _f =250μΑ		3.5		V

(1) Limited by wire bonding



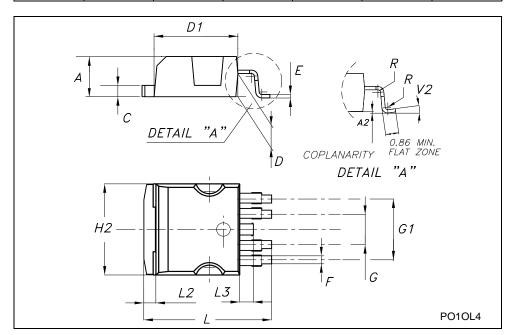
3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



DIM.	mm			inch		
Dini.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.30		4.80	0.169		0.188
A2	0.03		0.23	0.001		0.009
С	1.17		1.37	0.046		0.053
D	2.40		2.80	0.094		0.110
D1	8.95		9.35	0.352		0.368
E	0.35		0.55	0.013		0.021
F	0.80		1.05	0.031		0.041
G	3.20		3.60	0.125		0.141
G1	6.60		7.00	0.259		0.275
H2			10.40			0.409
L	13.59		14.39	0.535		0.566
L2	1.27		1.40	0.05		0.055
L3	1.30		1.70	0.051		0.066
R		0.30				

PENTAWATT SMD (P2PAK) MECHANICAL DATA



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4 Revision History

Date	Revision	Changes
22-Jul-2005	1	Initial release.



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